

# 型号: MT18SD-H

- MicroThin™为带有18 μm载体箔的超薄铜箔。  
MicroThin™ is ultra thin foil with 18 μm carrier foil.
- 适用于线宽/线距(L/S) = 35/35~40/40的应用。  
Usable for fine pitch pattern L/S = 35/35 - 40/40 formation.

## 用途/Application

- 半导体封装基板  
/Semiconductor Package
- 高密度多层基板  
/High Density Interconnect

## 构成/Composition



## 生产地点/Production Site

- 日本 / Japan
- 马来西亚/Malaysia

## 代表性特性数据/Representative data

Model No.	μm	Area weight (g/m <sup>2</sup> )	Laminate side Rz(μm)	Tensile Strength (N/mm <sup>2</sup> )	Elongation (%)	Peel Strength (kg/cm)@FR-4
MT18SD-H	3	39	3	-	-	1.4
	5	57	3	-	-	1.4

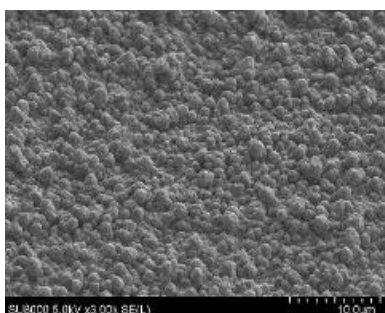
※上述列表为代表性数据，非保证数据。

This is representative data, not guaranteed.

※Peel Strength为增镀到35 μm厚度之后的测试值。

Evaluated after plated up to 35 μm.

处理面/Laminate side



阻剂面/Resist side

